Semilar   Contact Name   Title - Contact   Phone - Contact*   Phone - Contact*   Email - Contact*   Emailar - Contact*	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name	752-21.1										ials and Mi	fg Informat	ion		
Semilar   Semi	upplier Informa	ntion													
Title - Contact Name Product Envis Compliance NA Product Envis Compliance NA Product Envis Stewards Na Product Envis Compliance NA Product Envis Stewards © onsemi.com Na Nanufacturing Site Na Nanufacturing Proccess Information Nanufacturing Proccess Information Nanufacturing Proccess Information Natte Tin (Sn) - annealed OLy Int Internal Base Alloy I - STD-020 MSL Rating Natte Tin (Sn) - annealed Natte Tin (Sn) - annealed OLy Int Internal Base Alloy I - STD-020 MSL Rating Natte Tin (Sn) - annealed Natte Tin (Sn) - annealed OLy Int Internal Base Alloy I - STD-020 MSL Rating Natte Tin (Sn) - annealed Natte Tin (Sn) - annealed OLy Int Internal Base Alloy I - STD-020 MSL Rating Natte Tin (Sn) - annealed Natte Tin	Company name* Compa				ompany unique ID			Unique ID Authority				Response Date*			
Product Enviro Compliance Unitorized Representative* Title - Representative Title - Representative Product Enviro Compliance NA Product Enviro Compliance NA Product Enviro Compliance NA Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards NA Product Env-Stewards NA Product Env-Stewards NA Product Env-Stewards NA NSR1020MW2T1G SMALL SIG SCHOTTKY SOD323 Description NSR1020MW2T1G SMALL SIG SCHOTTKY SOD323 Description NSR1020MW2T1G SMALL SIG SCHOTTKY SOD323 Description NSR1020MSL Rating Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy  Terminal Plating soldering is 10-30 seconds	nsemi											2025-07-15			
Title - Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-E	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envis Compliance Requester Item Number Mfr Item Number Manufacturing Site Meight* Manufacturing Site Manu	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	tative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
NSR1020MW2T1G   SMALL SIG SCHOTTKY SOD323   2025-07-15   CN1   4.65   mg   Each	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles	Requester	Requester Item Number Mfr Iter		m Number Mfr Item Name				Effective Date	e Versio	on :	Manufacturing Site	V	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds  Somments  Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds		NSR1020MW2T1G SMALL SIG SCHOTTKY		OTTKY SOD	323	2025-07-15			CN1		l.65	mg	Each		
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vel 1 - maximum time at peak temperature during soldering is 10-30 seconds	•	(Sn) - annealed	C	U Alloy	I			200		JC	30	secon	18 <b>  3</b>		
<b>i i</b> 0 0		no at neak townsuct	dunina s-1-	donina ia 10-1	20 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.59	mg	Supplier	Silicon (Si)	7440-21-3		0.59	mg
Lead Frame	0.86	mg	В	Nickel (Ni)	7440-02-0		0.3483	mg
			Supplier	Iron (Fe)	7439-89-6		0.4773	mg
			Supplier	Copper (Cu)	7440-50-8		0.0344	mg
Mold Compound-Black	3.06	mg	Supplier	Boron zinc hydroxide oxide	138265-88-0		0.0918	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.0153	mg
			Supplier	2,4,6-triamino-s-triazincompd.withs-triazine-triol	37640-57-6		0.0918	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.448	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0306	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.2448	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1377	mg
Plating	0.13	mg	Supplier	Tin (Sn)	7440-31-5		0.13	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg